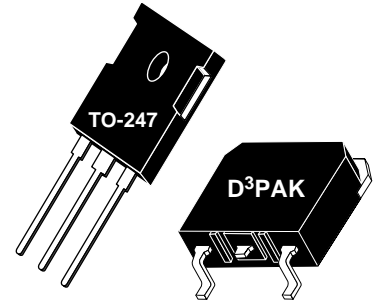
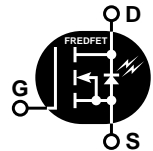


**POWER MOS V®**
**FREDFET**


Power MOS V® is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V® also achieves faster switching speeds through optimized gate layout.

- Fast Recovery Body Diode
- 100% Avalanche Tested
- Lower Leakage
- Faster Switching
- TO-247 or Surface Mount D<sup>3</sup>PAK Package



**MAXIMUM RATINGS**

 All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT5017BVFR_SVFR	UNIT
$V_{DSS}$	Drain-Source Voltage	500	Volts
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	30	Amps
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	120	
$V_{GS}$	Gate-Source Voltage Continuous	$\pm 30$	Volts
$V_{GSM}$	Gate-Source Voltage Transient	$\pm 40$	
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	370	Watts
	Linear Derating Factor	2.96	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current <sup>①</sup> (Repetitive and Non-Repetitive)	30	Amps
$E_{AR}$	Repetitive Avalanche Energy <sup>①</sup>	30	mJ
$E_{AS}$	Single Pulse Avalanche Energy <sup>④</sup>	1300	

**STATIC ELECTRICAL CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0V, I_D = 250\mu\text{A}$ )	500			Volts
$I_{D(on)}$	On State Drain Current <sup>②</sup> ( $V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10V$ )	30			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>②</sup> ( $V_{GS} = 10V, 0.5 I_{D[Cont.]}$ )			0.17	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = V_{DSS}, V_{GS} = 0V$ )			250	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_C = 125^\circ\text{C}$ )			1000	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30V, V_{DS} = 0V$ )			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}, I_D = 1.0\text{mA}$ )	2		4	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

## DYNAMIC CHARACTERISTICS

APT5017BVFR\_SVFR

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$		4400	5280	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 25V$		600	840	
$C_{rss}$	Reverse Transfer Capacitance	$f = 1\text{ MHz}$		230	350	
$Q_g$	Total Gate Charge <sup>③</sup>	$V_{GS} = 10V$		200	300	nC
$Q_{gs}$	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		30	45	
$Q_{gd}$	Gate-Drain ("Miller") Charge	$I_D = I_D [\text{Cont.}] @ 25^\circ\text{C}$		80	120	
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$		12	25	ns
$t_r$	Rise Time	$V_{DD} = 0.5 V_{DSS}$		14	30	
$t_{d(off)}$	Turn-off Delay Time	$I_D = I_D [\text{Cont.}] @ 25^\circ\text{C}$		55	80	
$t_f$	Fall Time	$V_G = 1.6\Omega$		11	20	

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)			30	Amps
$I_{SM}$	Pulsed Source Current <sup>①</sup> (Body Diode)			120	
$V_{SD}$	Diode Forward Voltage <sup>②</sup> ( $V_{GS} = 0V, I_S = -I_D [\text{Cont.}]$ )			1.3	Volts
$dv/dt$	Peak Diode Recovery $dv/dt$ <sup>⑤</sup>			5	V/ns
$t_{rr}$	Reverse Recovery Time ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		250	ns
		$T_j = 125^\circ\text{C}$		525	
$Q_{rr}$	Reverse Recovery Charge ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		1.6	$\mu\text{C}$
		$T_j = 125^\circ\text{C}$		6.0	
$I_{RRM}$	Peak Recovery Current ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		13	Amps
		$T_j = 125^\circ\text{C}$		21	

## THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.34	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Pulse Test: Pulse width < 380  $\mu\text{s}$ , Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

④ Starting  $T_j = +25^\circ\text{C}$ ,  $L = 2.89\text{mH}$ ,  $R_G = 25\Omega$ , Peak  $I_L = 30\text{A}$

⑤  $I_S \leq -I_D [\text{Cont.}]$ ,  $di/dt = 100\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DSS}$ ,  $T_j \leq 150^\circ\text{C}$ ,  $R_G = 2.0\Omega$ ,  $V_R = 200\text{V}$ .

APT Reserves the right to change, without notice, the specifications and information contained herein.

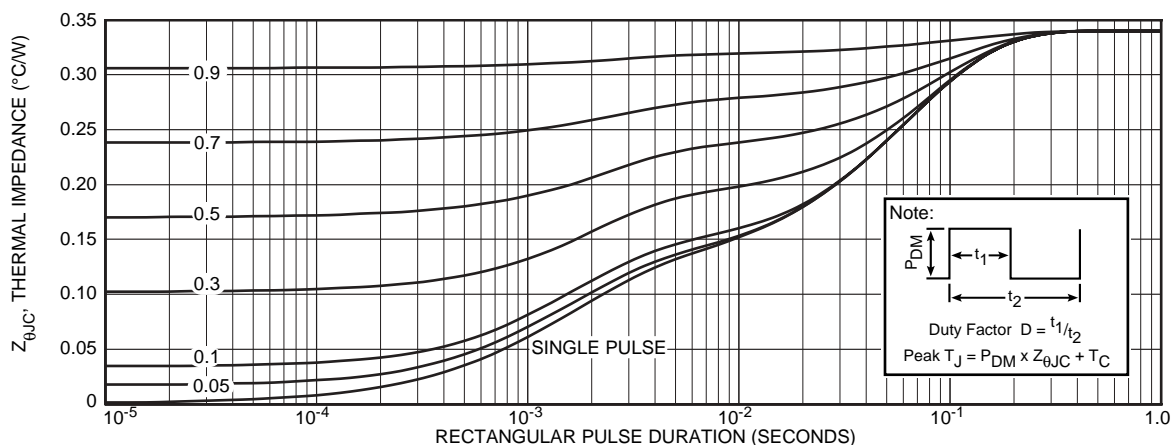


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

# Typical Performance Curves

APT5017BVFR\_SVFR

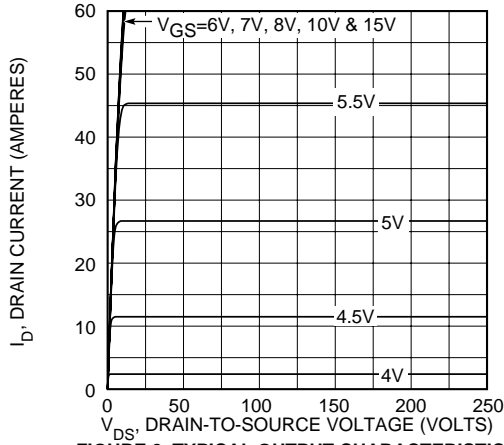


FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS

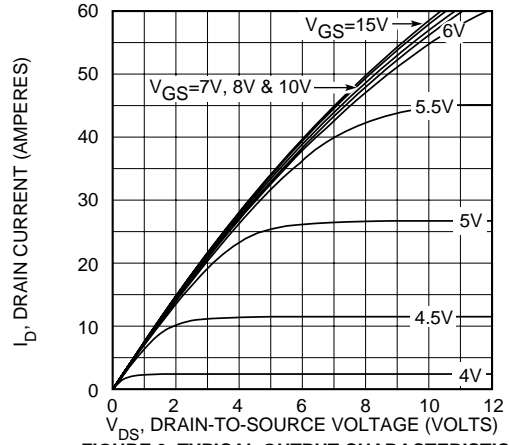


FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS

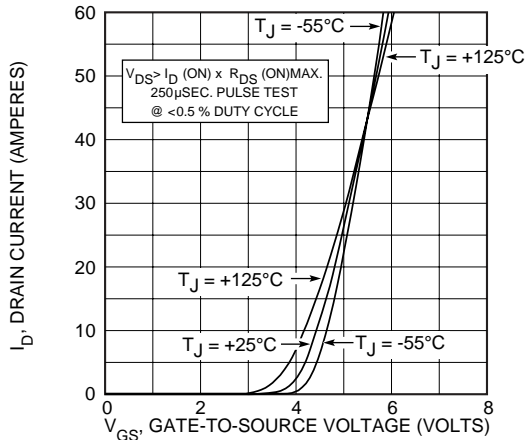


FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS

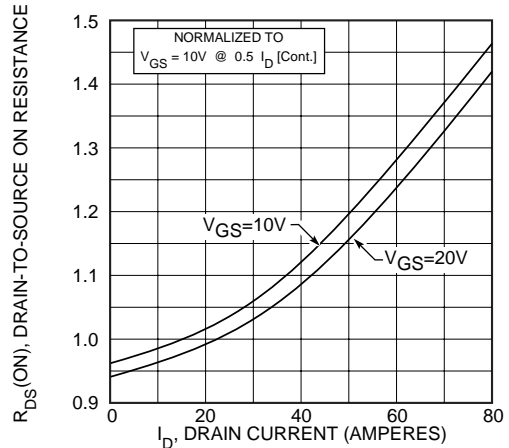


FIGURE 5,  $R_{DS(ON)}$  vs DRAIN CURRENT

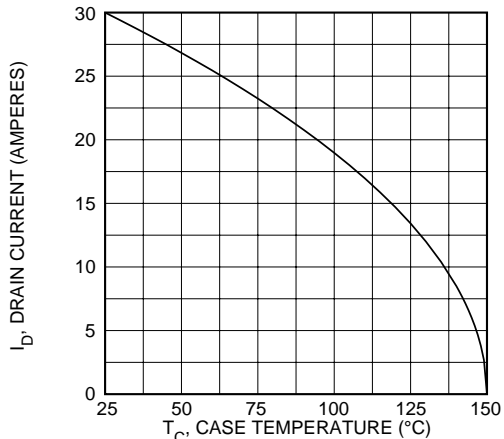


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

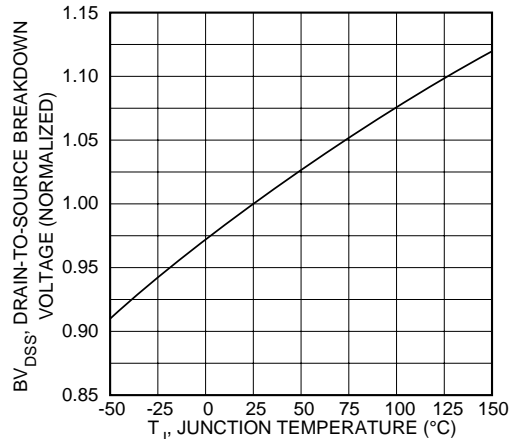


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

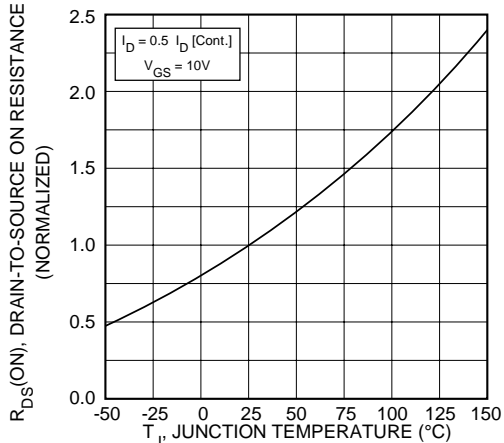


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

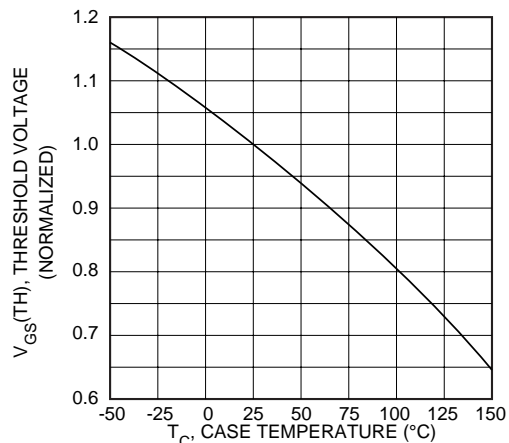


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

## Typical Performance Curves

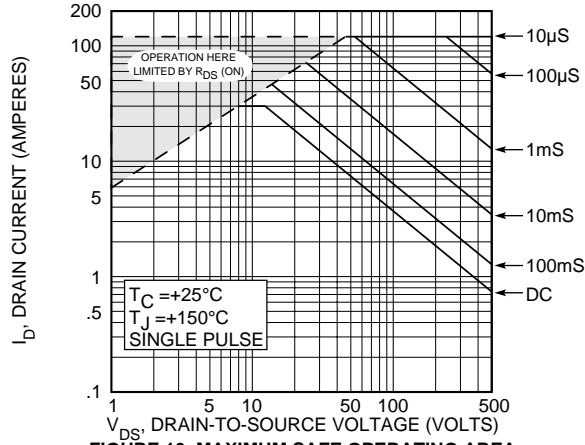


FIGURE 10, MAXIMUM SAFE OPERATING AREA

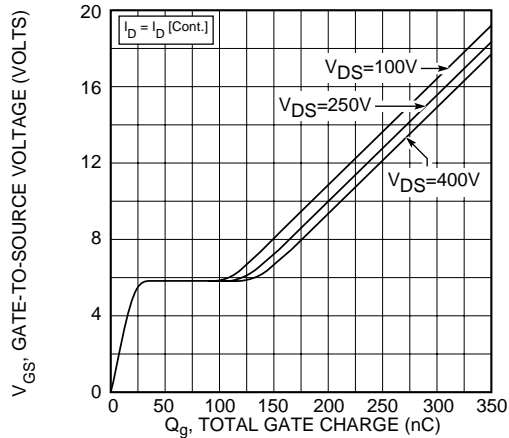


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

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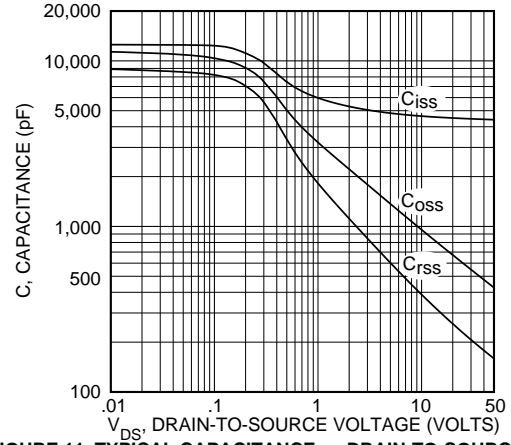


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

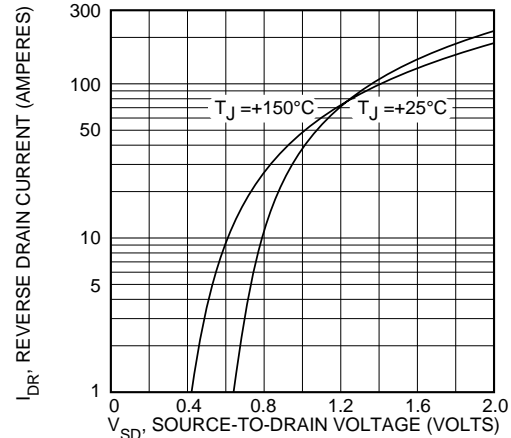
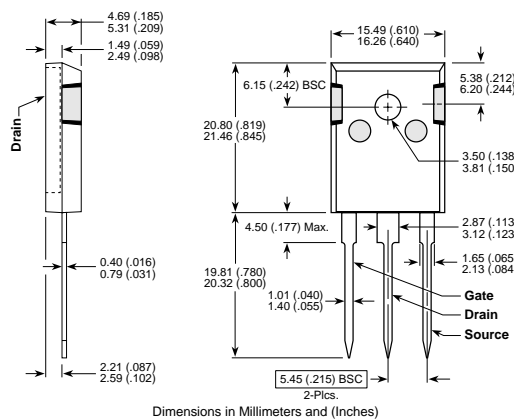
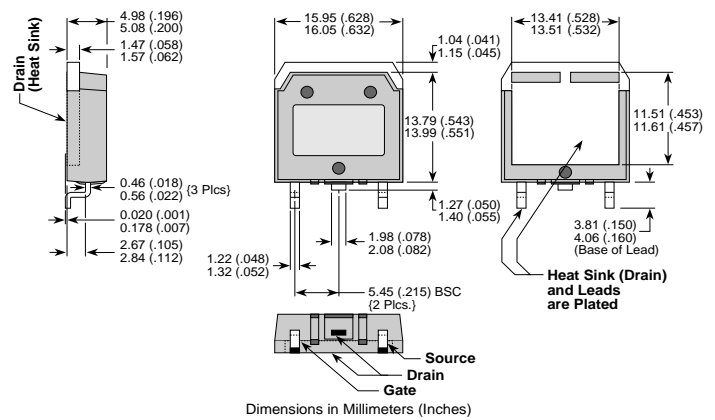


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

## TO-247 Package Outline



## D<sup>3</sup>PAK Package Outline



050-5547 Rev C 11-2003

APT's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522

5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. US and Foreign patents pending. All Rights Reserved.